

**IMPROVEMENTS IN AND RELATING TO GRINDING AND POLISHING
MACHINES**

ABSTRACT

A grinding machine for grinding the edge of a disc or wafer comprises a grooved grinding wheel 308, means for transporting the wafers before or after grinding, and a housing 332 in which wafers 340 are parked on a vacuum chuck 336 awaiting inspection. A jet 338 protrudes into the housing and directs water or air towards the face and edge of the wafer on the chuck. The transport means then transfers wafers to an inspection station.

FIGURE 1